

<b>Session Title:</b>	<b>[TC3] Metal Etching</b>
<b>Session Date:</b>	<b>November 15 (Tue.), 2022</b>
<b>Session Time:</b>	<b>14:30-16:10</b>
<b>Session Room:</b>	<b>Room C (Grand Ballroom 2, 2F)</b>
<b>Session Chair:</b>	<b>Prof. Kenji Ishikawa (Nagoya Univ., Japan)</b>

**[TC3-1] [Invited] 14:30-15:00**

**80 nm-Line Etching of Copper Thin Films Using Ethylenediamine/Acetic Acid/Ar Gas Mixture**

**Sung Young Park, Seon Jae Kim, Seung Hyun Kim, Su Hyun Song, and Chee Won Chung (Inha Univ., Korea)**

**[TC3-2] [Invited] 15:00-15:30**

**Alternative Approach for Low Temperature Copper Dry Etching with Large Sized ECR Plasma Source**

**Jin Nyoung Jang, Jae Hoon Jung, Jong Hwa Lee, Kiro Jung (APS Research Corp., Korea), Donghoon Kim (Korea Univ., Korea), Sang-Gab Kim (Samsung Display Co., Ltd., Korea), Soo Ouk Jang (KFE, Korea), Chiwoo Kim (APS Research Corp., Korea), and MunPyo Hong (Korea Univ., Korea)**

**[TC3-3] 15:30-15:50**

**Atomic Layer Etching of Sn Using H<sub>2</sub>/Cl<sub>2</sub> Radical**

**Yun Jong Jang, Doo San Kim, Hong Seong Gil, Hae In Kwon, Gyoung Chan Kim, and Geun Young Yeom (Sungkyunkwan Univ., Korea)**

**[TC3-4] 15:50-16:10**

**Clean Dry Etching of Ni Alloy Metal Thin Film for High Resolution Stretchable AMOLED**

**MupPyo Hong, Donghoon Kim, Sangheon Lee (Korea Univ., Korea), and Jin Nyoung Jang (APS Research Corp., Korea)**